Carrier for Receiving and Electrically Contacting Individually Separated Dies

ABSTRACT OF THE DISCLOSURE

The present invention relates to a carrier for receiving and electrically contacting individually separated dies (bare chips) for the testing and/or burn-in of the same, the carrier having first contacts arranged in a grid pattern corresponding to the die to be contacted. The preferred embodiment provides a carrier with which individually separated dies can be mechanically and electrically contacted with precision, allowing the functional testing and burn-in to be carried out with existing equipment, and in particular to realize the "known good die concept". The preferred embodiment is achieved by first contacts of the carrier being provided with elastomer bumps having second contacts on their tips. The second contacts are electrically connected to the first contacts, and the dies are drawn against the elastomer bumps by a predetermined force that is generated by a vacuum.